MCCOG128064B12W-SPTLY	128 x 64		LCD Module
Specification			
Version: 1		**Date: 01/10/2019**	
Revision			
29/09/2019	First Issue		

Display Features	
Resolution	128 x 64
Appearance	Black on Yellow/Green
Logic Voltage	3.3V
Interface	Parallel / SPI
Font Set	N/A
Display Mode	Transflective
LC Type	STN
Module Size	54.60 x 42.20 x 4.405 mm
Operating Temperature	-20°C ~ +70°C

Construction	COG	Box Quantity	Weight / Display
LED Backlight	Yellow/Green	---	---

RoHS compliant

* - For full design functionality, please use this specification in conjunction with the ST7565P specification. (Provided Separately)

Display Accessories	
Part Number	**Description**
MCIB-12	UNO 32 Breakout Board with SD Card and LED BKL driver.
MPBV-7	30-Way FFC to Cable and Wires 0.5mm Pitch.
MCCOG128064B-BEZEL	Bezel made for the MCCOG12064B series
MDC28-0.5-BC	28 way connector with 0.5mm pitch.

Optional Variants	
Appearances	**Voltage**
White on Blue Black on White Black on RGB	

General Specification

The Features is described as follow:

- Module dimension: 54.6 x 42.2 x 4.405 mm

- View area: 50.6 x 31.0 mm

- Active area: 46.577 x 27.697 mm

- LCD type: STN Positive, Yellow Green Transflective

- Duty/ Bias: 1/65 DUTY,1/7BIAS

- View direction: 12 o'clock

- Backlight Type: LED Yellow Green

- IC:ST7565P

Interface Pin Function

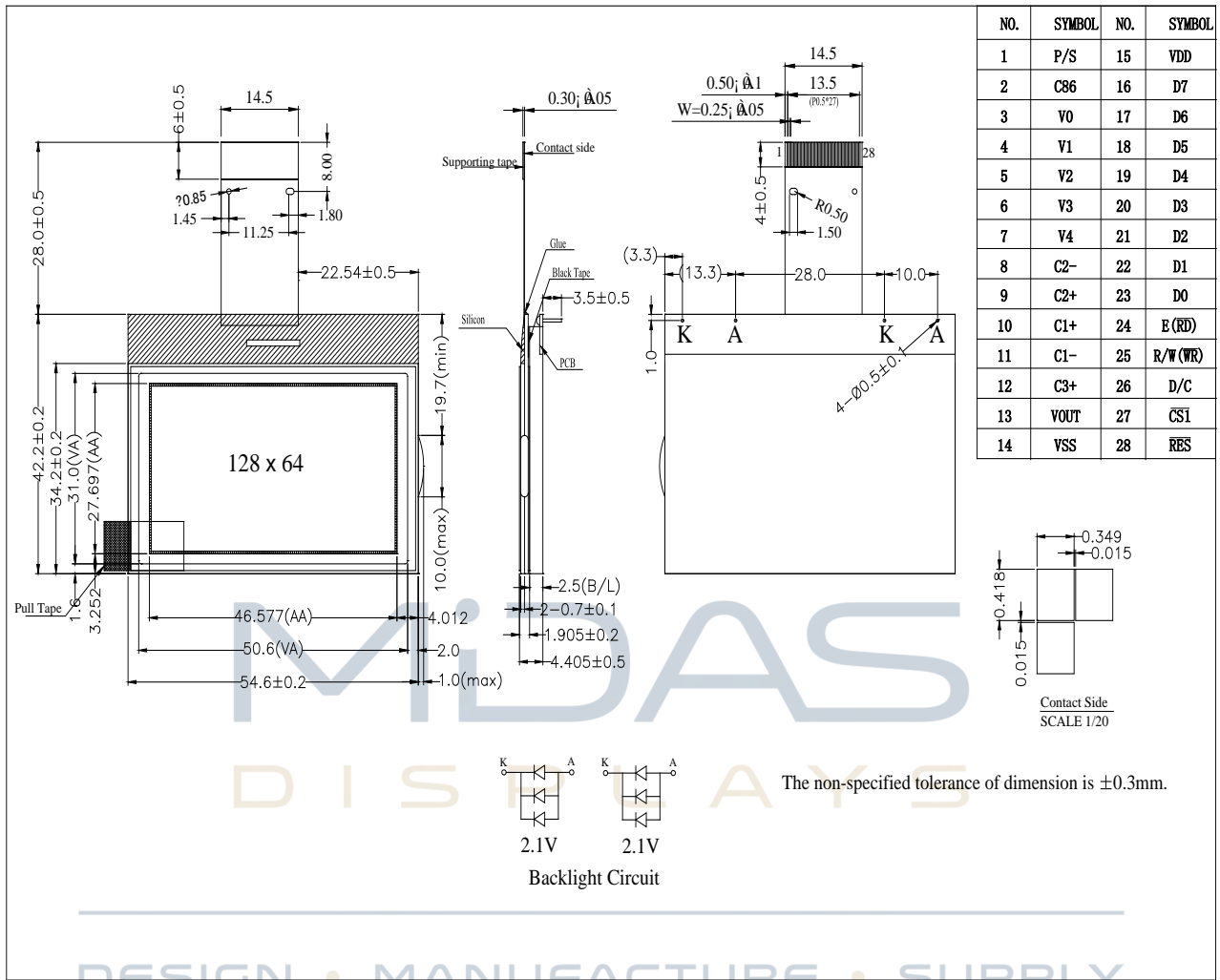| Pin No.	Symbol	Description
1	P/S	This pin configures the interface to be parallel mode or serial mode. P/S = "H": Parallel data input/output. P/S = "L": Serial data input.
2	C86	This is the MPU interface selection pin. C86 = "H": 6800 Series MPU interface. C86 = "L": 8080 Series MPU interface.
3	V0	This is a multi-level power supply for the liquid crystal drive. The voltage Supply applied is determined by the liquid crystal cell, and is changed through the use of a resistive voltage divided or through changing the impedance using an op. amp. Voltage levels are determined based on Vss, and must maintain the relative magnitudes shown below. $V0 \geqq V1 \geqq V2 \geqq V3 \geqq V4 \geqq Vss$
4	V1	
5	V2	
6	V3	
7	V4	
8	C2-	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP2P terminal
9	C2+	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP2N terminal.
10	C1+	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1N terminal.
11	C1-	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1P terminal.
12	C3+	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1N terminal.
13	VOUT	Voltage converter input/output pin Connect this pin to VSS through capacitor.
14	VSS	Ground
15	VDD	Power supply
16	D7	This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit Standard MPU data bus. When the serial interface (SPI-4) is selected (P/S = "L") : D7 : serial data input (SI) ; D6 : the serial clock input (SCL). D0 to D5 should be connected to VDD or floating.
17	D6	
18	D5	
19	D4	

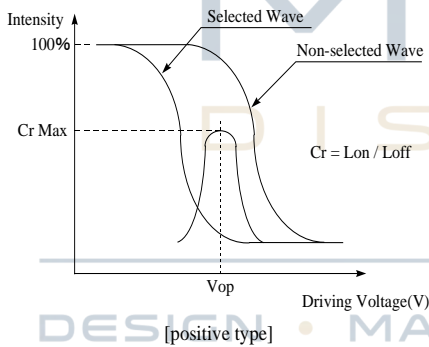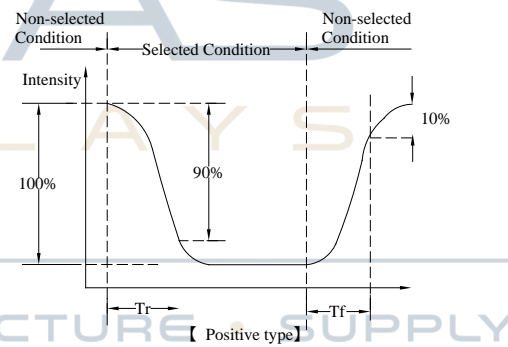| 20	D3	When the chip select is not active, D0 to D7 are set to high impedance.
21	D2	
22	D1	
23	D0	
24	E(/RD)	When connected to 8080 series MPU, this pin is treated as the "/RD" signal of the8080 MPU and is LOW-active. The data bus is in an output status when this signal is "L". When connected to 6800 series MPU, this pin is treated as the "E" signal of the6800 MPU and is HIGH-active.This is the enable clock input terminal of the 6800 Series MPU.
25	R/W(/WR)	When connected to 8080 series MPU, this pin is treated as the "/WR" signal of the8080 MPU and is LOW-active. The signals on the data bus are latched at the rising edge of the /WR signal. When connected to 6800 series MPU, this pin is treated as the "R/W" signal of the6800 MPU and decides the access type : When R/W = "H": Read. When R/W = "L": Write
26	D/C	This is connect to the least significant bit of the normal MPU address bus, and it determines whether the data bits are data or command.
27	/CS1	This is the chip select signal
28	/RES	When /RES is set to "L", the register settings are initialized (cleared). The reset operation is performed by the /RES signal level.

Contour Drawing

NO.	SYMBOL	NO.	SYMBOL
1	P/S	15	VDD
2	C86	16	D7
3	V0	17	D6
4	V1	18	D5
5	V2	19	D4
6	V3	20	D3
7	V4	21	D2
8	C2−	22	D1
9	C2+	23	D0
10	C1+	24	E(RD)
11	C1−	25	R/W(WR)
12	C3+	26	D/C
13	VOUT	27	CS1
14	VSS	28	RES

128 x 64

Contact side

Supporting tape

Glue

Black Tape

Silicon

PCB

Pull Tape

14.5
6±0.5
8.00
0.85
1.45
11.25
1.80
22.54±0.5
28.0±0.5
42.2±0.2
34.2±0.2
31.0(VA)
27.697(AA)
1.6
3.252
46.577(AA)
50.6(VA)
54.6±0.2
4.012
2.0
1.0(max)
19.7(min)
10.0(max)

0.30¡À05
3.5±0.5
2.5(B/L)
2−0.7±0.1
1.905±0.2
4.405±0.5

14.5
0.50¡À1
W=0.25¡À05
13.5
(P0.5*27)
1
28
4±0.5
R0.50
1.50
(3.3)
(13.3)
28.0
10.0
K A K A
1.0
4−Ø0.5±0.1

0.349
0.015
0.418
0.015

Contact Side
SCALE 1/20

The non-specified tolerance of dimension is ±0.3mm.

K A K A
2.1V 2.1V

Backlight Circuit

Optical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
View Angle	θ	CR≧2	0	─	45	ψ= 180°
	θ	CR≧2	0	─	25	ψ= 0°
	θ	CR≧2	0	─	35	ψ= 90°
	θ	CR≧2	0	─	35	ψ= 270°
Contrast Ratio	CR	─	3	─	─	─
Response Time	T rise	─	─	─	250	ms
	T fall	─	─	─	250	ms

Definition of Operation Voltage (Vop)   **Definition of Response Time (Tr , Tf)**

Intensity
100%
Selected Wave
Non-selected Wave
Cr Max
Cr = Lon / Loff
Vop
Driving Voltage(V)
[positive type]

Non-selected Condition
Selected Condition
Non-selected Condition
Intensity
100%
90%
10%
Tr
Tf
【 Positive type】

Conditions :

Operating Voltage : Vop   Viewing Angle(θ，φ) : 0°， 0°

Frame Frequency : 64 HZ Driving Waveform : 1/N duty , 1/a bias

Definition of viewing angle(CR≧2)

θ f
θ b
φ = 180°
θ l
θ r
φ = 270°
φ = 90°
φ = 0°
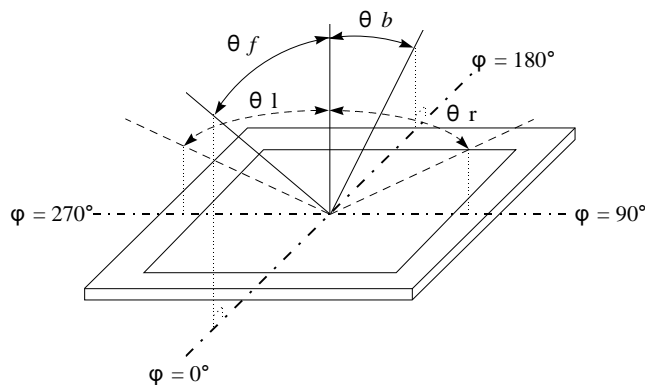
Absolute Maximum Ratings

Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	T_{OP}	-20	—	+70	℃
Storage Temperature	T_{ST}	-30	—	+80	℃
Power Supply Voltage	VDD	-0.3	—	3.6	V
Power supply voltage (VDD standard)	V0, VOUT	-0.3	—	14.5	V
Power supply voltage (VDD standard)	V1, V2, V3, V4	-0.3	—	V0+0.3	V

Electrical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage For Logic	$V_{DD}-V_{SS}$	—	3.2	3.3	3.4	V
Supply Voltage For LCM	V_{OP}	Ta=-20℃	—	—	—	V
		Ta=25℃	8.5	8.7	8.9	V
		Ta=70℃	—	—	—	V
Supply Current	I_{DD}	V_{DD}=3.3V	—	0.1	—	mA

Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance

Backlight Information

Specification

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	—	96	120	mA	V=2.1V
Supply Voltage	V	1.9	2.1	2.3	V	—
Reverse Voltage	VR	—	—	3.0	V	—
Wave Length	λp	565	570	575	nm	ILED=96mA
Luminance (Without LCD)	IV	80	100	—	CD/M²	ILED=96mA
LED Life Time (For Reference only)	—	—	50K	—	Hr.	ILED=96mA 25℃,50-60%RH, (Note 1)
Color	Yellow Green					

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.
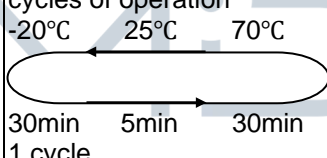
LED B\L Drive Method
1.Drive from A , K
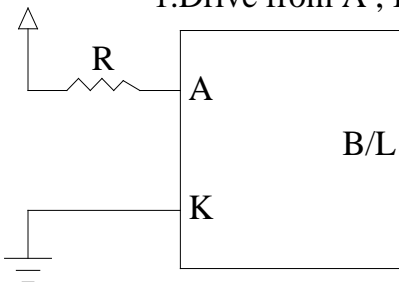
Reliability

Content of Reliability Test (Wide temperature, -20℃~70℃)

Environmental Test			
Test Item	**Content of Test**	**Test Condition**	**Note**
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80℃ 200hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30℃ 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 200hrs	――
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20℃ 200hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60℃,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60℃,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20℃　　25℃　　70℃ 30min　　5min　　30min 1 cycle	-20℃/70℃ 10 cycles	――
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times	――
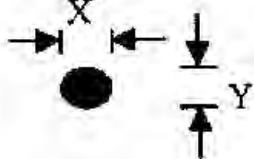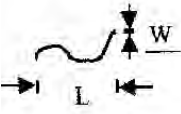
Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal
　　　　Temperature and humidity after remove from the test chamber.
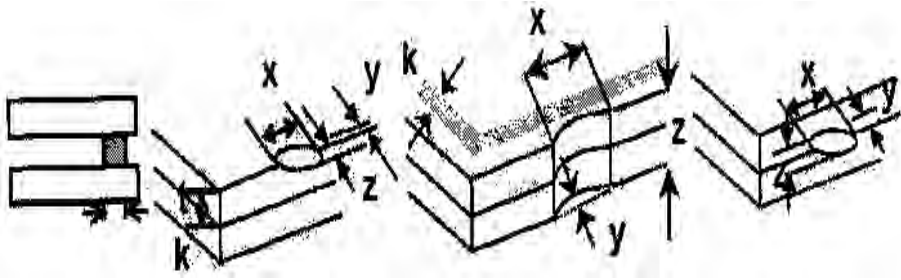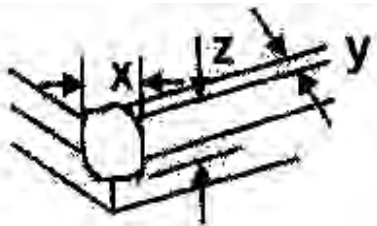
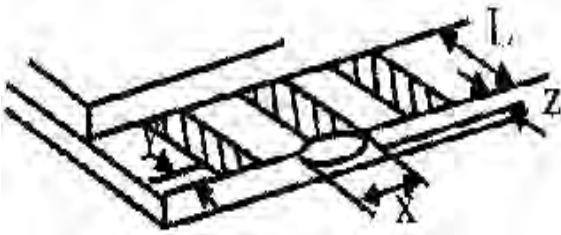**Note3: The packing have to including into the vibration testing.**

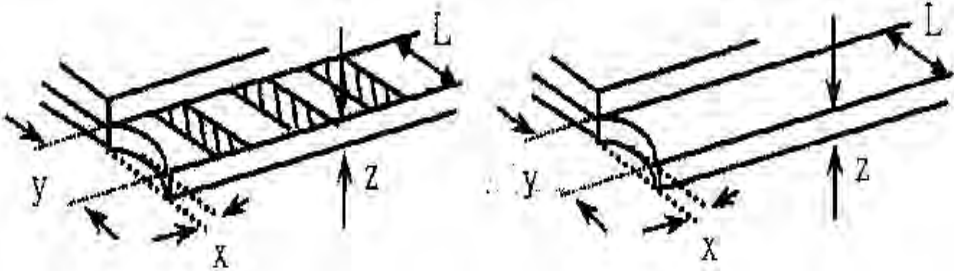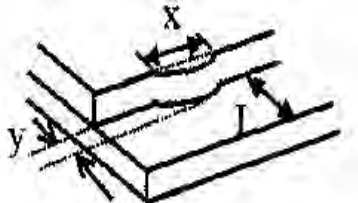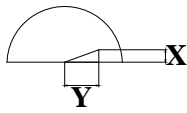# Inspection specification

NO	Item	Criterion	AQL
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character , dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect.	0.65
02	Black or white spots on LCD (display only)	2.1 White and black spots on display $\leqq$0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm	2.5

NO	Item	Criterion		AQL
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type : As following drawing $\Phi=(x + y) / 2$	<table><tr><td>SIZE</td><td>Acceptable Q TY</td></tr><tr><td>$\Phi\leqq0.10$</td><td>Accept no dense</td></tr><tr><td>$0.10<\Phi\leqq0.20$</td><td>2</td></tr><tr><td>$0.20<\Phi\leqq0.25$</td><td>1</td></tr><tr><td>$0.25<\Phi$</td><td>0</td></tr></table>	2.5
		3.2 Line type : (As following drawing)	<table><tr><td>Length</td><td>Width</td><td>Acceptable Q TY</td></tr><tr><td>---</td><td>$W\leqq0.02$</td><td>Accept no dense</td></tr><tr><td>$L\leqq3.0$</td><td>$0.02<W\leqq0.03$</td><td rowspan="2">2</td></tr><tr><td>$L\leqq2.5$</td><td>$0.03<W\leqq0.05$</td></tr><tr><td>---</td><td>$0.05<W$</td><td>As round type</td></tr></table>	2.5
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.	<table><tr><td>Size Φ</td><td>Acceptable Q TY</td></tr><tr><td>$\Phi\leqq0.20$</td><td>Accept no dense</td></tr><tr><td>$0.20<\Phi\leqq0.50$</td><td>3</td></tr><tr><td>$0.50<\Phi\leqq1.00$</td><td>2</td></tr><tr><td>$1.00<\Phi$</td><td>0</td></tr><tr><td>Total Q TY</td><td>3</td></tr></table>	2.5

NO	Item	Criterion	AQL
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination	
06	Chipped glass	Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length: 6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels:	2.5

z: Chip thickness	y: Chip width	x: Chip length
$Z \leqq 1/2t$	Not over viewing area	$x \leqq 1/8a$
$1/2t < z \leqq 2t$	Not exceed 1/3k	$x \leqq 1/8a$

⊙If there are 2 or more chips, x is total length of each chip.

6.1.2 Corner crack:

z: Chip thickness	y: Chip width	x: Chip length
$Z \leqq 1/2t$	Not over viewing area	$x \leqq 1/8a$
$1/2t < z \leqq 2t$	Not exceed 1/3k	$x \leqq 1/8a$

⊙If there are 2 or more chips, x is the total length of each chip.

NO	Item	Criterion	AQL
06	Glass crack	Symbols : x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal : 6.2.1 Chip on electrode pad :	2.5

Symbols :

x: Chip length   y: Chip width   z: Chip thickness

k: Seal width   t: Glass thickness   a: LCD side length

L: Electrode pad length

6.2 Protrusion over terminal :

6.2.1 Chip on electrode pad :

y: Chip width	x: Chip length	z: Chip thickness
$y \leqq 0.5mm$	$x \leqq 1/8a$	$0 < z \leqq t$

6.2.2 Non-conductive portion:

y: Chip width	x: Chip length	z: Chip thickness
$y \leqq L$	$x \leqq 1/8a$	$0 < z \leqq t$

⊙If the chipped area touches the ITO terminal, over 2/3 of the ITO
   must remain and be inspected according to electrode terminal
   specifications.

⊙If the product will be heat sealed by the customer, the alignment
   mark not be damaged.

6.2.3 Substrate protuberance and internal crack.

y: width	x: length
$y \leqq 1/3L$	$x \leqq a$

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB X * Y<=2mm2	2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.	2.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	2.5
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	0.65
		12.12 Visual defect outside of VA is not considered to be rejection.	

DESIGN • MANUFACTURE • SUPPLY

Precautions in use of LCD Modules

(1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.

(2) Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.

(3) Don't disassemble the LCM.

(4) Don't operate it above the absolute maximum rating.

(5) Don't drop, bend or twist LCM.

(6) Soldering: only to the I/O terminals.

(7) Storage: please storage in anti-static electricity container and clean environment.

(8) Midas have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors,capacitors and other passive components will have different appearance and color caused by the different supplier.)

(9) Midas have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Midas have the right to modify the version.)

(10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.

DESIGN · MANUFACTURE · SUPPLY

Material List of Components for RoHs

1. Midas Displays hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A：The Harmful Material List

Material	Cd	Pb	Hg	Cr6+	PBB	PBDE	DEHP	BBP	DBP	DIBP
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.										

2. Process for RoHS requirement：(only for RoHS inspection)
   (1) Use the Sn/Ag/Cu soldering surface；the surface of Pb-free solder is rougher than we used before.
   (2) Heat-resistance temp. ：
      Reflow：250℃,30 seconds Max.；
      Connector soldering wave or hand soldering：320℃, 10 seconds max.
   (3) Temp. curve of reflow, max. Temp. ：235±5℃；
      Recommended customer's soldering temp. of connector：280℃, 3 seconds.

Recommendable Storage

1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
2. Do not place the module near organics solvents or corrosive gases.
3. Do not crush, shake, or jolt the module.